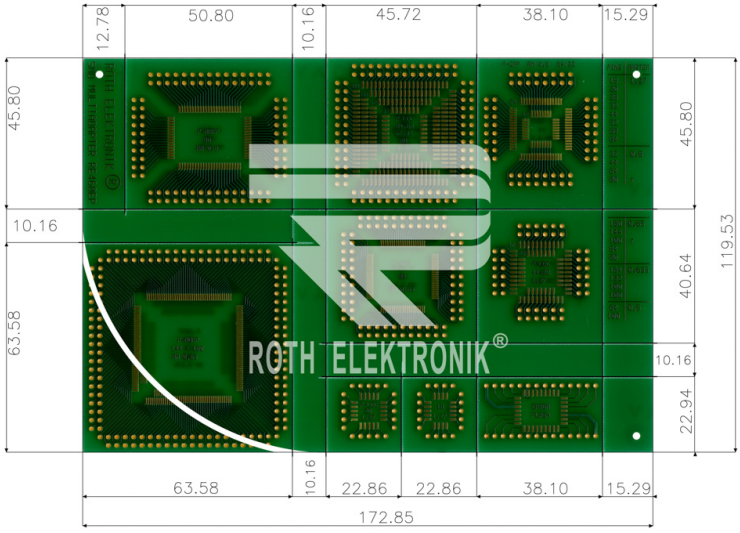


**RE460**

- Epoxy fibre-glass FR4 1.50 mm
- Double-sided 35 µm Cu
- Plated through holes (PTH)
- Surface chem. Ni/Au and solder stop mask
- Pitches from 0.50 to 1.27 mm
- Hole diameter 1.00 mm
- Adaption board for 23 different SMD-IC's
- Prescratched rated break point for the separation of individual modules from the board
- Manual soldering: as for the SMD individual processing in the laboratory area, a freehanded coating of 100 to 200 single spots with precise metering hoppers is possible with grids from 0.50 to 1.27 mm
- Reflow soldering by means of purpose made separate SMD templates
- Size 120 x 175 mm

| Module-No. | Pitch | Pin |
|---|---|---|
| RE460-01 | 0.800 mm | QFP 32, 80 |
| | 0.500 mm | QFP 64 |
| RE460-02 | 0.800 mm | QFP 80 |
| | 0.650 mm | QFP 100 |
| RE460-03 | 0.650 mm | QFP 80, 84 |
| RE460-04 | 0.650 mm | QFP 144, 160 |
| | 0.635 mm | QFP 100, 132, 164 |
| RE460-05 | 1.270 mm | PLCC 32, 52, 68, 84 |
| | 0.635 mm | QFP 100 |
| | 0.500 mm | QFP 100 |
| RE460-06 | 1.270 mm | PLCC 28, 44 |
| | 0.800 mm | QFP 44 |
| RE460-07 | 1.270 mm | PLCC 18 |
| RE460-08 | 1.270 mm | PLCC 20 |
| RE460-09 | 1.270 mm | PLCC-Eprom 32 |



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***BIC*** GENODEF1HH2